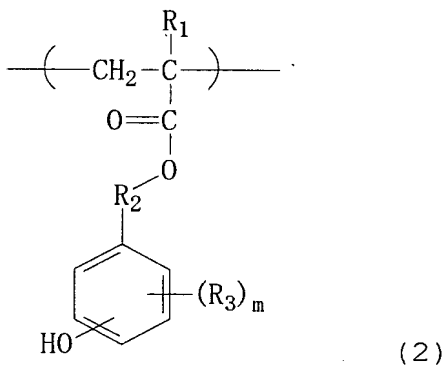
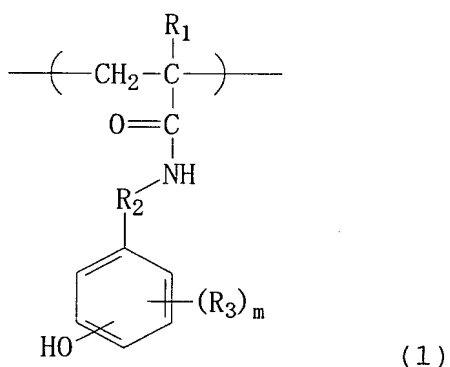


What is claimed is:

1. A negative radiation-sensitive resin composition comprising:

(A) a polymer containing structural units represented by the following formula (1) and/or the following formula (2):



wherein R₁ is a hydrogen atom or a methyl group, R₂ is -
 10 (CH₂)_n-, n is an integer of 0 to 3, R₃ is an alkyl group of 1 to 4 carbon atoms, and m is an integer of 0 to 4,

(B) a compound having at least one ethylenically unsaturated double bond, and

(C) a radiation-sensitive radical polymerization initiator.

2. The negative radiation-sensitive resin
5 composition as claimed in claim 1, which is a composition
for producing a plated shaped article.

3. The negative radiation-sensitive resin
composition as claimed in claim 2, wherein the plated
10 shaped particle is a bump.

4. The negative radiation-sensitive resin
composition as claimed in claim 1, wherein the component
(B) is contained in an amount of 30 to 80 parts by weight
15 based on 100 parts by weight of the component (A).

5. The negative radiation-sensitive resin
composition as claimed in claim 1, wherein the component
(C) is contained in an amount of 15 to 30 parts by weight
20 based on 100 parts by weight of the component (A).

6. The negative radiation-sensitive resin
composition as claimed in claim 1, which further
comprises an organic solvent (D).

7. A transfer film having a resin film composed of the negative radiation-sensitive resin composition of claim 1 on a support film.

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8. The transfer film as claimed in claim 7, wherein the resin film has a film thickness of 5 to 200 μm .

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9. A process for producing a plated shaped article, comprising:

(1) a step of forming a resin film composed of the negative radiation-sensitive resin composition of claim 1 on a wafer having a barrier metal layer,

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(2) a step of exposing the resin film and then developing the resin film to form a pattern,

(3) a step of depositing an electrode material by electroplating using the pattern as a mold, and

(4) a step of stripping the remaining resin film and then removing the barrier metal by etching.

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